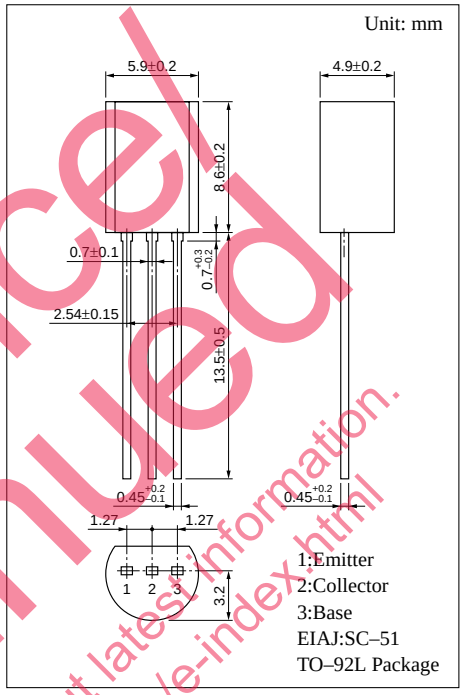
2SA1487

Silicon PNP epitaxial planer type

For video amplifier



Features

- High transition frequency f_T.
- Small collector output capacitance C_{ob}.

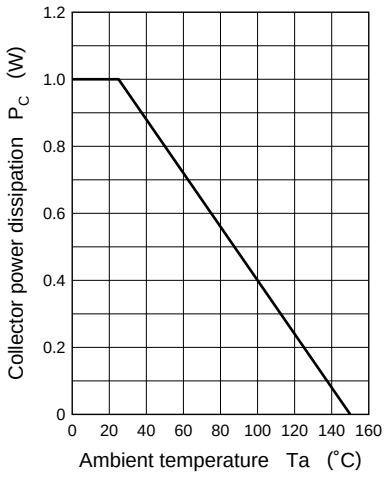
Absolute Maximum Ratings (Ta=25˚C)

Parameter	Symbol	Ratings	Unit
Collector to base voltage	V_{CBO}	–85	V
Collector to emitter voltage	V_{CEO}	–85	V
Emitter to base voltage	V_{EBO}	–4	V
Peak collector current	I_{CP}	–100	mA
Collector current	I_C	–50	mA
Collector power dissipation	P_C	1	W
Junction temperature	T_j	150	˚C
Storage temperature	T_{stg}	–55 ~ +150	˚C

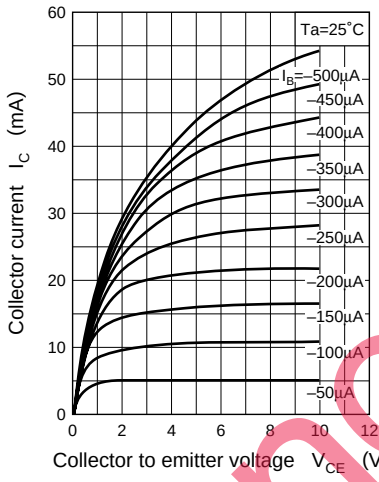
Electrical Characteristics (Ta=25˚C)

Parameter	Symbol	Conditions	min	typ	max	Unit
Collector cutoff current	I_{CEO}	V_{CE} = –60V, I_B = 0			–10	µA
Collector to base voltage	V_{CBO}	I_C = –100µA, I_E = 0	–85			V
Collector to emitter voltage	V_{CEO}	I_C = 1mA, I_B = 0	–85			V
Emitter to base voltage	V_{EBO}	I_E = –100µA, I_C = 0	–4			V
Forward current transfer ratio	h_{FE}	V_{CE} = –5V, I_C = –10mA	60			
Collector to emitter saturation voltage	$V_{CE(sat)}$	I_C = –10mA, I_B = –1mA			– 0.5	V
Transition frequency	f_T	V_{CB} = –5V, I_E = 10mA, f = 200MHz		500		MHz
Collector output capacitance	C_{ob}	V_{CB} = –10V, I_E = 0, f = 1MHz		2.7		pF

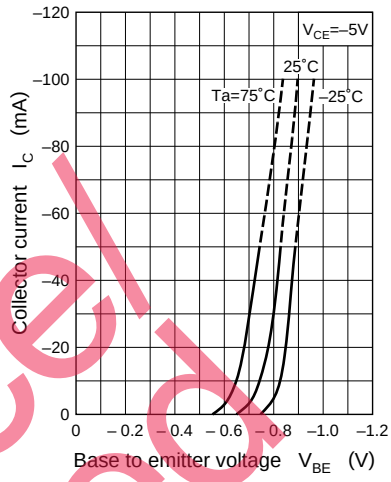
P_C — Ta



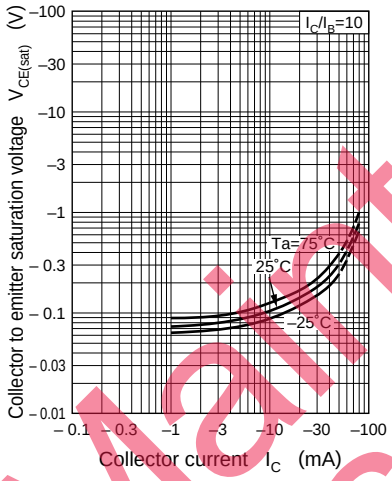
I_C — V_{CE}



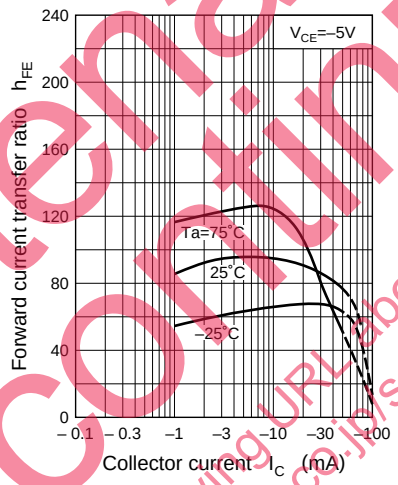
I_C — V_{BE}



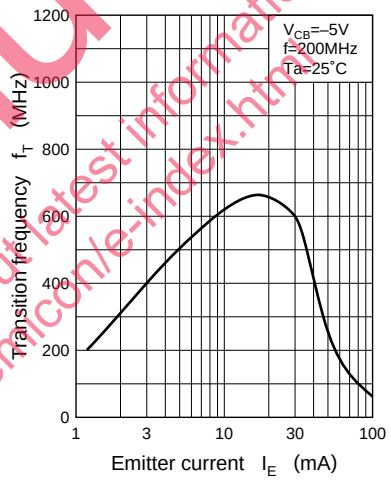
$V_{CE(sat)}$ — I_C



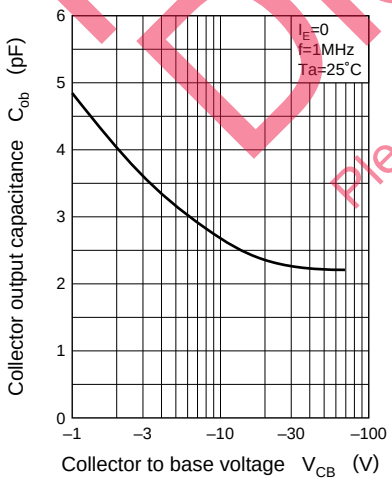
h_{FE} — I_C



f_T — I_E



C_{ob} — V_{CB}



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